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3-27-02
Makai

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:
Todd O. Bolken

Serial No.: 09/516,080

Filed: March 1, 2000

For: EXPOSED DIE MOLDING
APPARATUS



Group Art Unit: 2814

Examiner: Louie, W.

Atty Docket: MICS:0043 FLE/MAN
99-0634

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Assistant Commissioner
for Patents
Washington, D.C. 20231

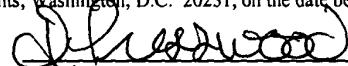
Sir:

CERTIFICATE OF MAILING
37 C.F.R. 1.8

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as First Class Mail in an envelope addressed to: Assistant Commissioner for Patents, Washington, D.C. 20231, on the date below:

March 1, 2002

Date


Jennifer Presswood

RESPONSE AND AMENDMENT

In response to the Official Action mailed on December 5, 2001, Applicants respectfully request reconsideration of the above-identified application in view of the remarks and amendments set forth below.

IN THE DRAWINGS

In Figs. 6A and 6B, replace reference numeral 90 with reference numeral 95.

IN THE CLAIMS

Please amend claims 1, 5, 9, 10 and 11 as set forth below:

1. (once amended) A system for molding a circuit package comprising: